

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

ABS2-MS THRU ABS10-MS

Product specification

SURFACE MOUNT ULTRAFAST RECTIFIER

VOLTAGE:400V TO 600V

CURRENT: 3.0A

PACKAGE OUTLINE



ABS

Features

- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- High temperature soldering guaranteed: 260°C/10 seconds at 5 lbs., (2.3kg) tension
- Small size, simple installation
- High surge current capability
- Glass passivated chip junction
- Green compound(halogen&Sb2O3 free)

Mechanical Data

Case: Molded plastic body

Terminals: Plated leads solderable per MIL-STD-750, Method 2026

Polarity: Polarity symbols marked on case

Mounting Position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load derate current by 20%.

	SYMBOLS	ABS2-MS	ABS4-MS	ABS6-MS	ABS8-MS	ABS10-MS	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	$I_{F(AV)}$	0.8 1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30					A
Maximum instantaneous forward voltage dropper leg at 0.4A	V_F	0.95					V
Maximum DC reverse current at rated DC blocking voltage	I_R	5 100					uA uA
Typical thermal resistance(NOTE 3)	R_{JL} R_{JA}	25 75					°C/W
Operating temperature range	T_J	-55 to +150					°C
storage temperature range	T_{STG}	-55 to +150					°C

NOTES:1.On glass epoxy P.C.B. mounted on 0.05x0.05"(1.3x1.3mm) pads
2.On aluminum substrate P.C.B. with an area of 0.8"x0.8"(20x20mm) mounted on 0.05X0.05"(1.3X1.3mm) solder pad
3.Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2"(5X5mm) copper pads.

RATINGS AND CHARACTERISTIC CURVES ABS2-MS THRU ABS10-MS

FIG.1 FORWARD DERATING CURVE

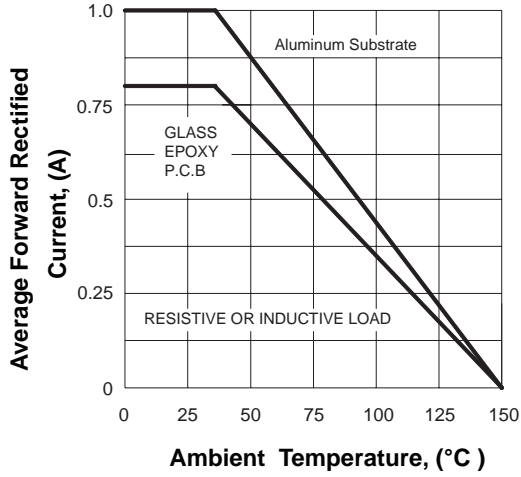


FIG.2 PEAK FORWARD SURGE CURRENT

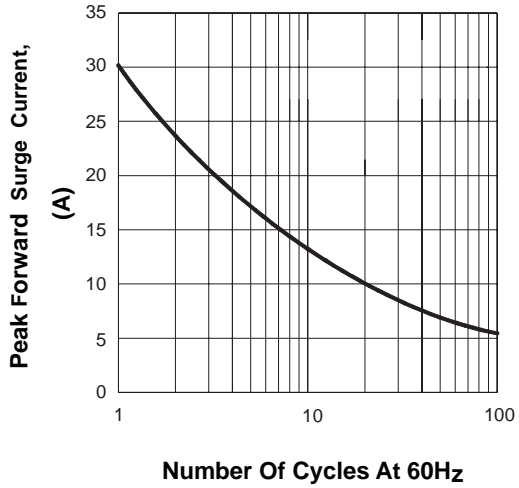


FIG.3 TYPICAL FORWARD CHARACTERISTICS

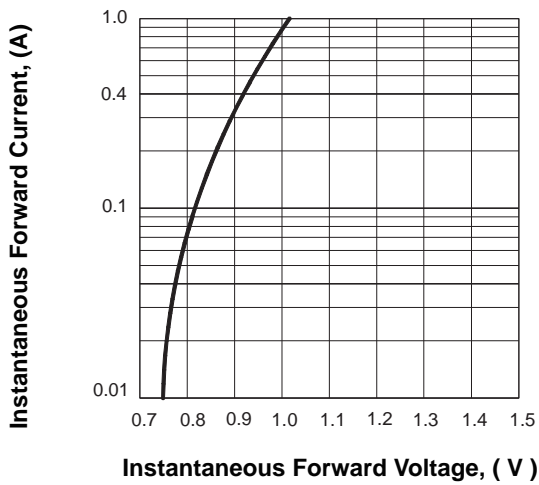
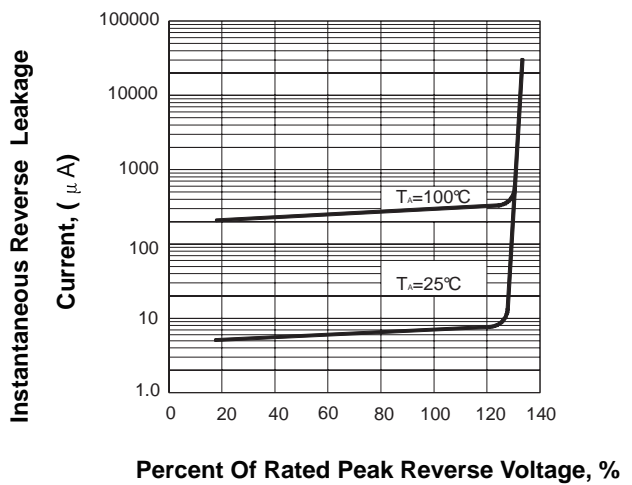
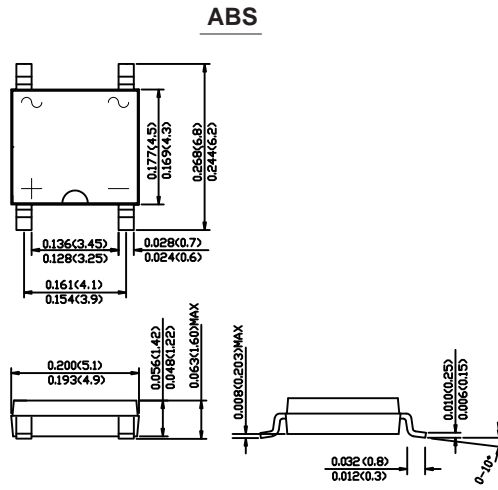


FIG.4 TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



Dimensions in inches and (millimeters)

REEL SPECIFICATION

P/N	PKG	QTY
ABS2-MS THRU ABS10-MS	ABS	5000

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